Device for Coating a Wafer

Abstract

The invention relates to a device for coating a surface (2o) of a wafer (2)

- With a retaining system (16) for placing the wafer (2) on a retaining surface (19), and
- A nozzle system (10) for coating the wafer (2) in a Z-direction, characterized in that

on a side periphery (2a) of the wafer (2), a ring (4) that surrounds the wafer (2) with an inside periphery (4i) can be arranged for expanding a coating surface when coating the wafer (2).

Figure 1.